

SUSS Investor Presentation

October 2026



Company Overview





SUSS at a glance



- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

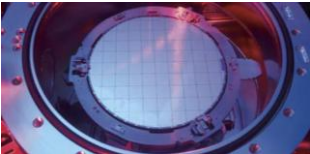
SUSS is part of our digital life!

Milestones in our company's history



1949

Company founded as Karl Süss KG in Munich



1990

Volume production of wafer bonder starts



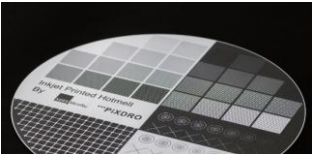
2000

Coating systems added through acquisition of Fairchild Technologies



2010

Second German site established after acquisition of Hamatech APE



2020

Inkjet printing added to coating expertise through acquisition of PiXDRO



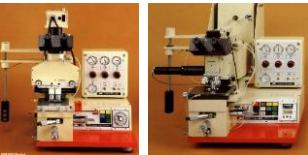
2024

Relaunch of the brand as SUSS



2026

Introduction of SUSS eco-friendly wafer cleaning technology GreenTec Solutions



1963

World's first mask aligner SUSS MJB3 developed



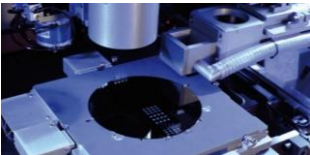
1999

Initial Public Offering at the Frankfurt Stock Exchange completed



2001

Company renamed to SUSS MicroTec



2012

Projection scanner technology taken over from Tamarack Scientific



2020

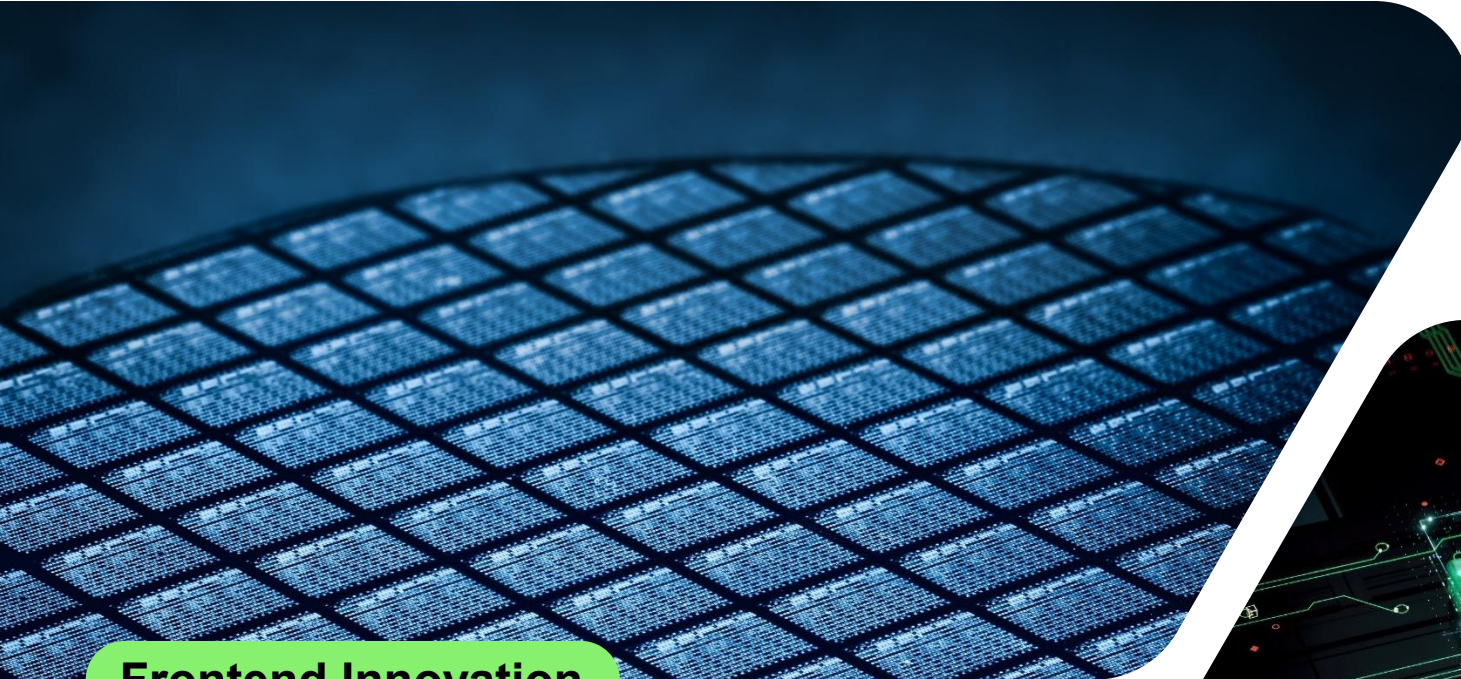
Asian production site opened in Hsinchu/Taiwan



2025

Opening of new and larger site in Zhubei/Taiwan

We are fully committed to driving the next chapter of innovation and growth in frontend (Moore's Law) and backend (More than Moore)

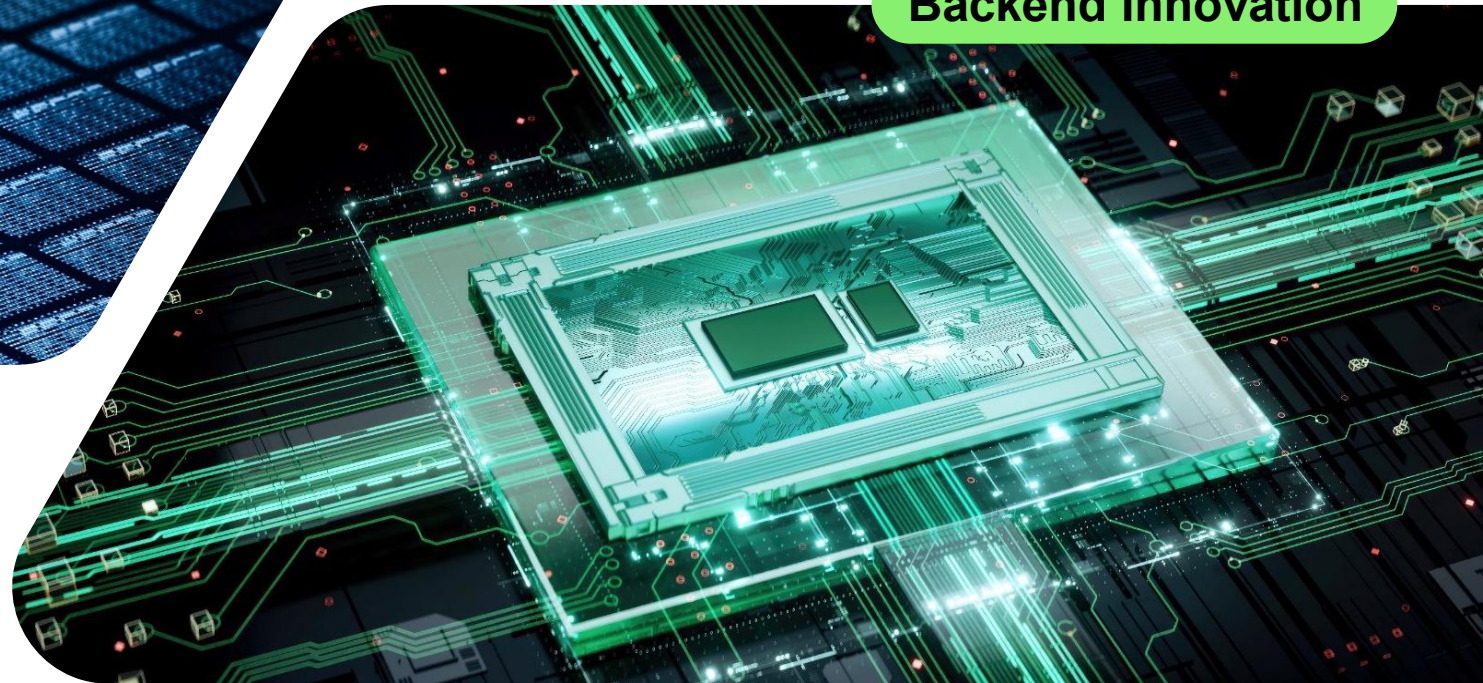


Frontend Innovation

Striving for the next technology node

Heterogeneous integration
creates new multi-chip modules

Backend Innovation



Our two segments, fully focused on the semiconductor industry

SEGMENTS



PRODUCTS & PROCESS STEPS

PHOTOMASK SOLUTIONS	GREENTEC SOLUTIONS	BONDING SOLUTIONS	COATING SOLUTIONS	IMAGING SOLUTIONS
• Photomask Cleaning • Post Exposure Bake • Develop • Pellicle Glue Removal	• Wafer Cleaning	• Bond Alignment • Permanent Bonding • Temporary Bonding • Debonding	• Coating / Developing • Inkjet Printing	• Proximity Exposure (Mask Aligner) • UV Projection (Scanner)

Management Board



CFO
Dr. Cornelia Ballwießer

- Finance & Controlling
- Legal
- Compliance
- Internal Audit
- Risk Management & ICS
- IT
- ESG



CEO
Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Investor Relations & Communications
- Business Units:
Advanced Backend Solutions,
Photomask Solutions



COO
Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

Photomask Solutions Portfolio Highlights



Clean
Strip
Develop

HMx Series



Clean
Strip Develop
PEB

Asx Series

SUSS portfolio includes photomask solutions from laboratory to high volume production. Our scalable solutions can support the next technology nodes.



Bake
Develop
AI Analysis

MaskTrack Smart BD



Pellicle Glue
Removal

MaskTrack X GB



Clean
Strip
Bake
Develop

MaskTrack PRO / X

GreenTec Solutions Portfolio Highlights



Resist Strip
&
Post Clean

GreenTec is launching the GT200, a 200 mm wafer cleaning platform combining SUSS's patented technologies with a hybrid single-wafer and bath cleaning approach for a broad range of 200mm applications.

GT200

Advanced Backend Solutions

Portfolio Highlights – Imaging Systems



MASK
ALIGNER

MA/BA8 Gen4



PROJECTION
SCANNER

DSC300 Gen3

With over 60 years of innovation SUSS offers superior exposure solutions from laboratory to high volume production.



MASK
ALIGNER

MA200 Gen3



MASK
ALIGNER

MA300 Gen3

Advanced Backend Solutions

Portfolio Highlights – Coating Systems

**ACS200 Gen3 TE****COATER/
DEVELOPER****ACS300 Gen2****COATER/
DEVELOPER**

SUSS has the unique capability to offer tailored coating solutions for spin, spray and inkjet coating – depending on application needs.

**ECD8****COATER/
DEVELOPER****JETx****INKJET
PRINTER****ACS200 Gen3 TE -
JETx****COATER/
INKJET PRINTER**

Advanced Backend Solutions

Portfolio Highlights – Bonding Systems



SUSS is market leader for temporary bonding and de-bonding solutions and complements the portfolio with permanent & hybrid bonding equipment.



SUSS hybrid bonding solutions – understanding customer's needs



Wafer-to-wafer HB XBS300 W2W

Product launched: 10/2022
Target customers: HVM



Die-to-wafer/wafer-to-wafer HB XBC300 Gen2 D2W/W2W

Product launched: 05/2024
Target customers: Research
institutes, R&D teams of HVM



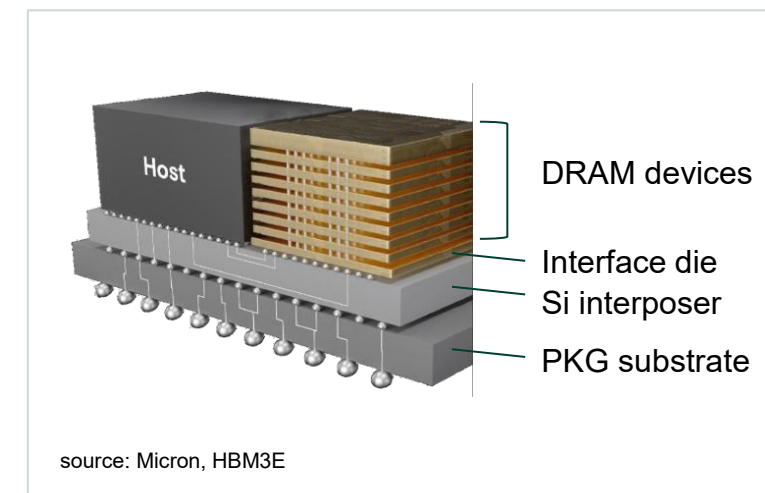
Die-to-wafer HB XBC300 Gen2 D2W

Product launched: 5/2025
Target customers: HVM

We optimize our product solutions to serve our customer's device and manufacturing needs.

HBM roadmap enables SUSS to grow in existing and new markets

	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2026	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB and HB	TCB and HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



Relevance for SUSS:

1

TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

2

Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

Additional growth of SUSS TBDB business in line with higher layer in HBM cube

3

Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

2.5/3D Chiplet Technology | SUSS well positioned to benefit from the strong momentum in 2.5D and 3D evolution

Temporary Bonding

- **HBM:** Structural support during thinning

Hybrid Bonding

- **HBM:** Stacking of DRAMs¹
- **CPO:** Stacking of PIC & EIC¹
- **SoIC:** E.g., Logic-on-Logic¹

Inkjet-/Spin Coating

- **TIV:** Lithography
- **RDL:** Lithography¹

UV-Scanner (Exposure)

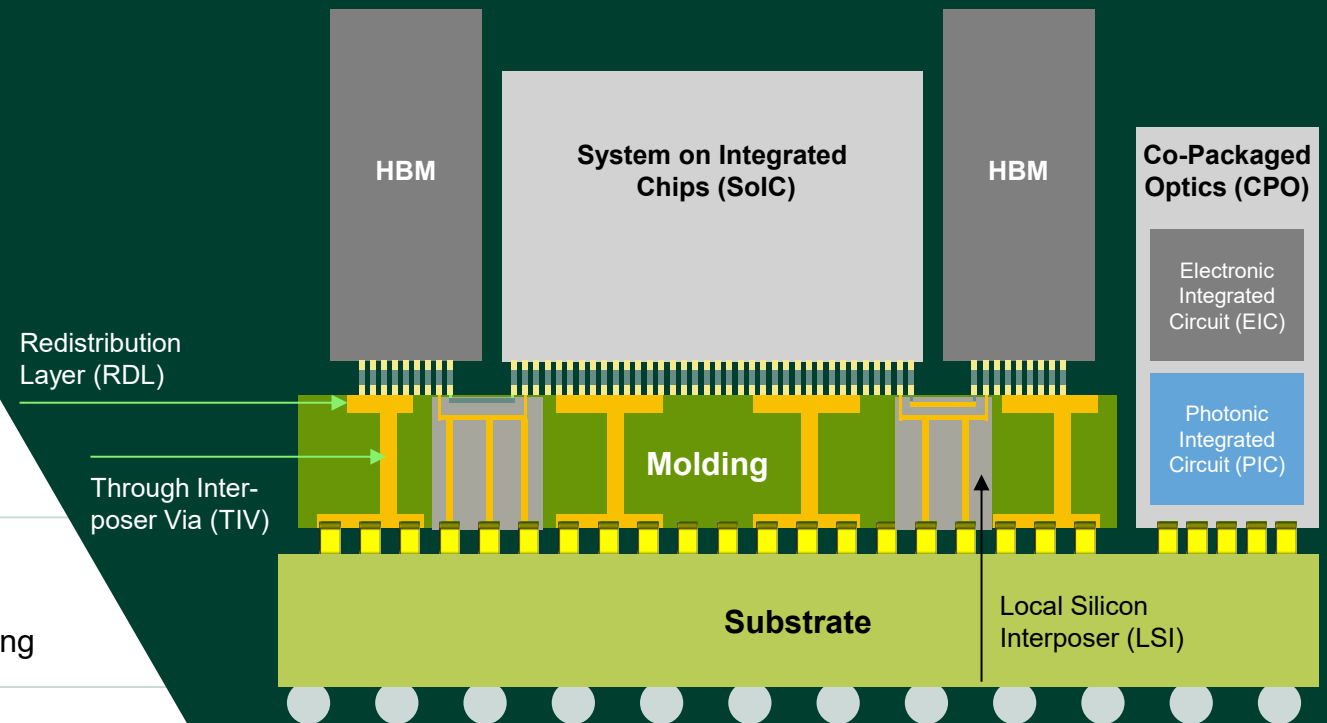
- **TIV:** Lithography
- **RDL:** Lithography¹

Photomask Cleaning (Frontend)

- **HBM:** Mask Cleaning in DRAM manufacturing
- **SoIC:** Mask Cleaning in Logic manufacturing

Wafer Cleaning

- **HBM:** Critical material removal and final cleaning in Backend manufacturing¹



¹ Potential future use case

● BU Advanced Backend Solutions

● BU Photomask Solutions

Our three manufacturing sites for semiconductor equipment



	 Garching HQ, Germany	 Sternenfels Germany	 Zhubei Taiwan
Photomask Cleaning		 MaskTrack X	
Bonding Systems		 XBC300	>  XBS300
Coating Systems			 ACS300
Imaging Systems	 Mask Aligner MA200/300		 UV Projection Scanner DSC300
Operations employees 2025	48	176	175

The new application center: a strategic investment into innovation and future growth

Located in Karlsruhe, close to the KIT-Campus, SUSS will invest €45 million until 2028.



First rendering of the planned application and development center in Karlsruhe. The illustration is subject to change as planning progresses.

Innovation Hub:

- Access to key talents and leading semiconductor research through professorship at KIT
- Accelerates product development and innovation cycles
- Strengthens long-term technology leadership

Capacity for Growth:

- Relocation of R&D and application activities to Karlsruhe
- Frees up cleanroom space in Sternenfels

Platform for the Future:

- Improves collaboration between development and customers
- Enables long-term growth in Advanced Packaging

Financials H1 2026



H1 2026 at a glance:

Record Order Intake of 410.0 million in the first six months

Financial Results

H1 2026

Order Intake

410.0

in € million

+145.8% YoY

Sales

202.8

in € million

-23.9% YoY

Gross Profit Margin

37.2

in %

-0.8 % YoY

EBIT Margin

7.0

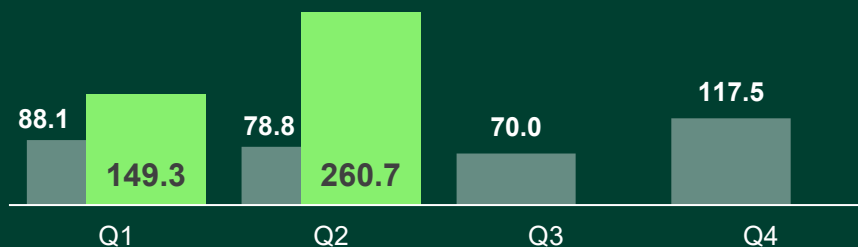
in %

-9.5 pp YoY

Q2 2026 delivered significantly higher sales and profitability than Q1

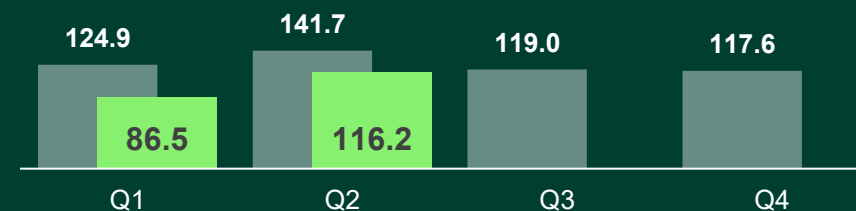
Order intake
(Q2 2026)

Group **€260.7m**

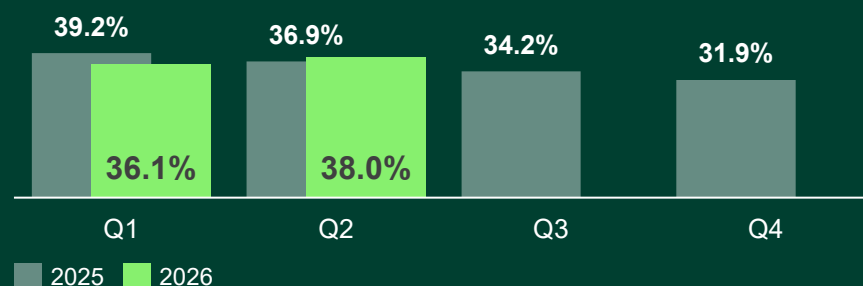


Sales
(Q2 2026)

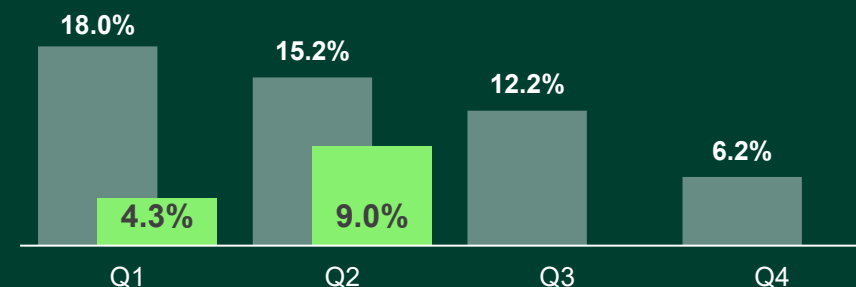
€116.2m



Gross profit margin
38.0% (Q2 2026)



EBIT margin
9.0% (Q2 2026)



■ 2025 ■ 2026

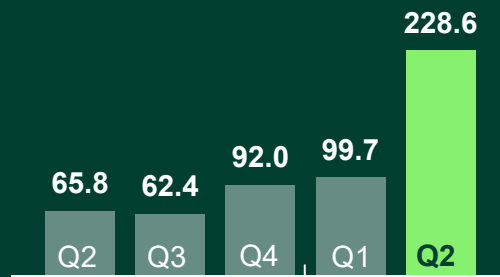
The prior-year figures have been adjusted.

Strong order intake and rising sales in Advanced Backend Solutions

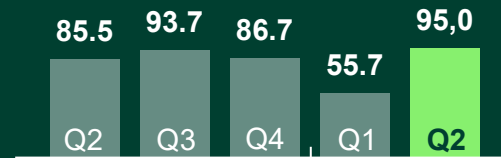
Segments

Advanced Backend Solutions

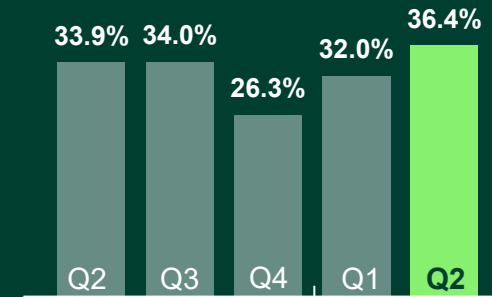
Order intake by quarters



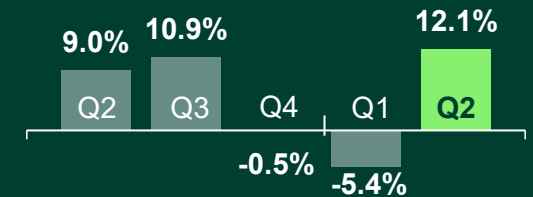
Sales by quarters



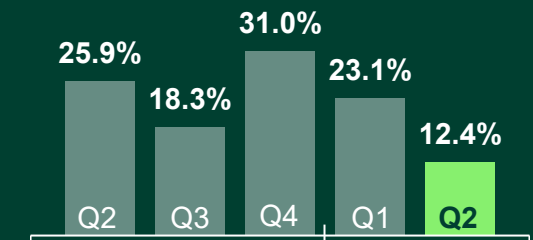
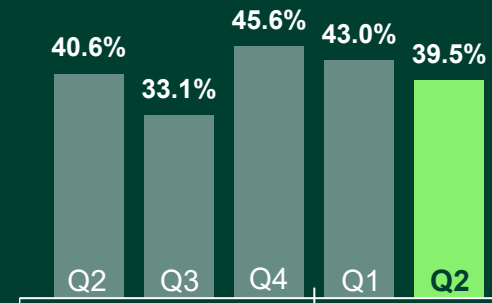
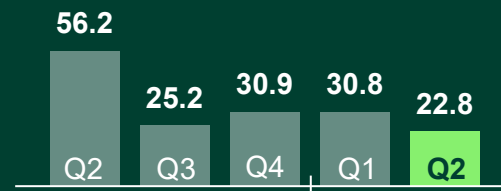
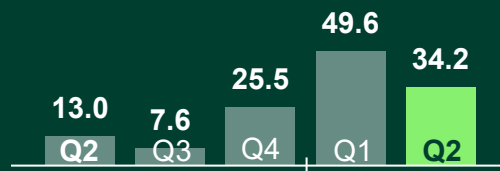
Gross profit margin by quarters



EBIT margin by quarters



Photomask Solutions



The prior-year figures have been adjusted.

Transition year 2026: A temporary dip in sales is expected, leading to lower fixed-cost coverage and, together with rising R&D expenses, to a lower EBIT margin while the gross profit margin remains broadly stable

Guidance 2026

(as of March 30, 2026)

Sales
in € million

425–485

Actual 2025:
€ 503.2 million

**Gross profit
margin** in %

35–37

Actual 2025:
35.7%

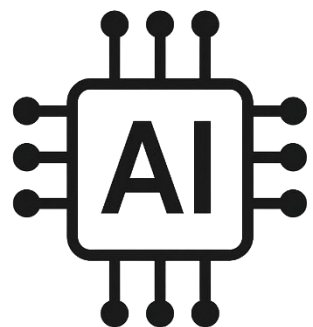
EBIT margin
in %

8–10

Actual 2025:
13.1%

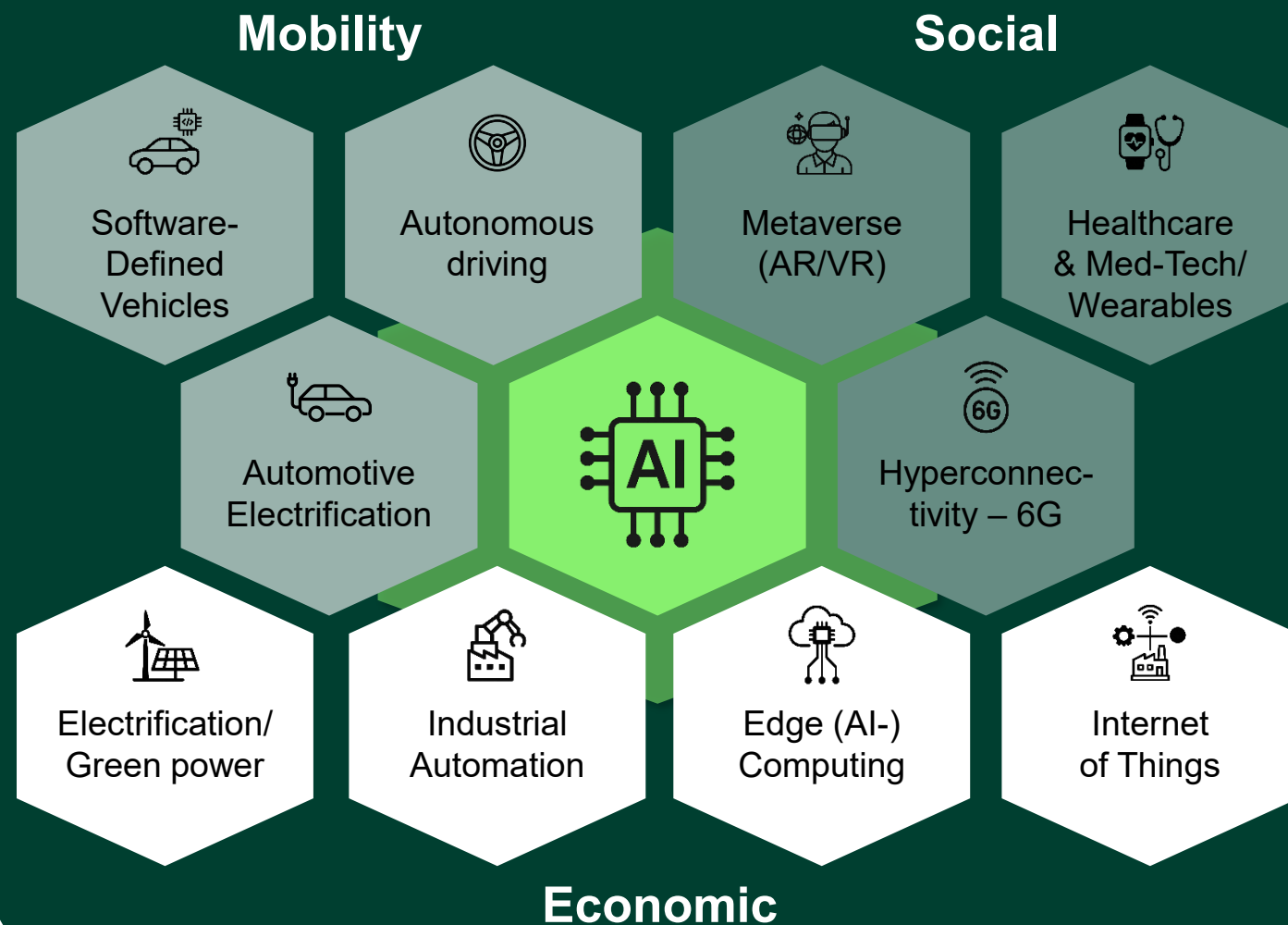
Market outlook and Ambition 2030





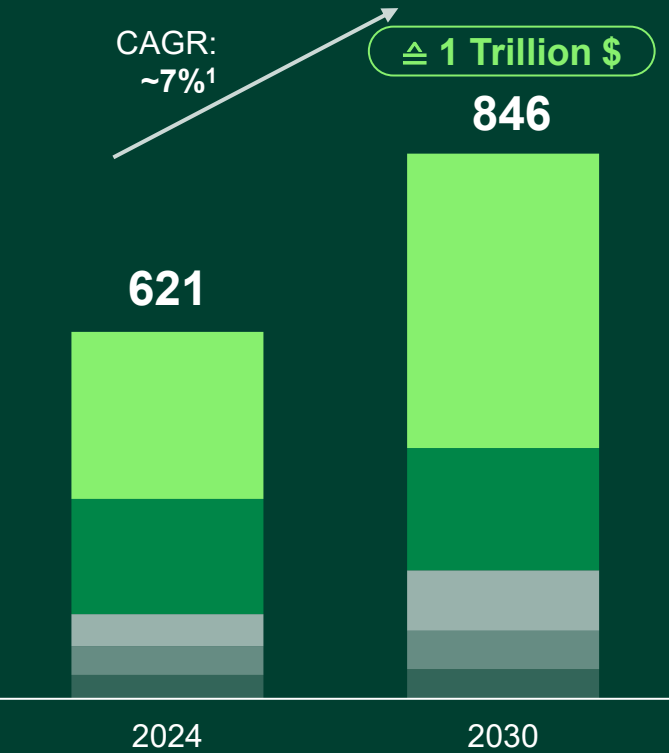
**Today's tech trends,
accelerated by AI, are
built on semiconductors**
Fueling rapid growth across the
semiconductor ecosystem

Trend Selection – not exhaustive



AI-led secular trends are driving semiconductors toward a \$1 trillion market by 2030

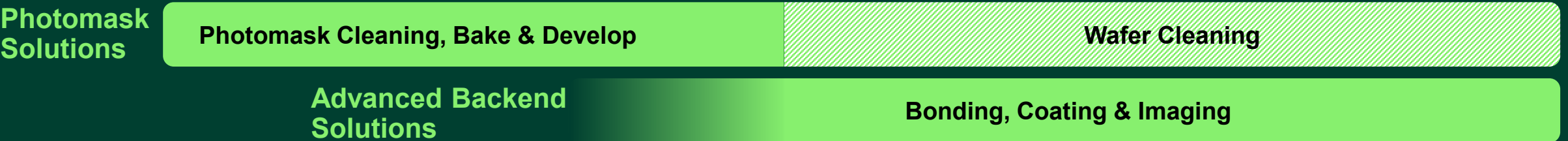
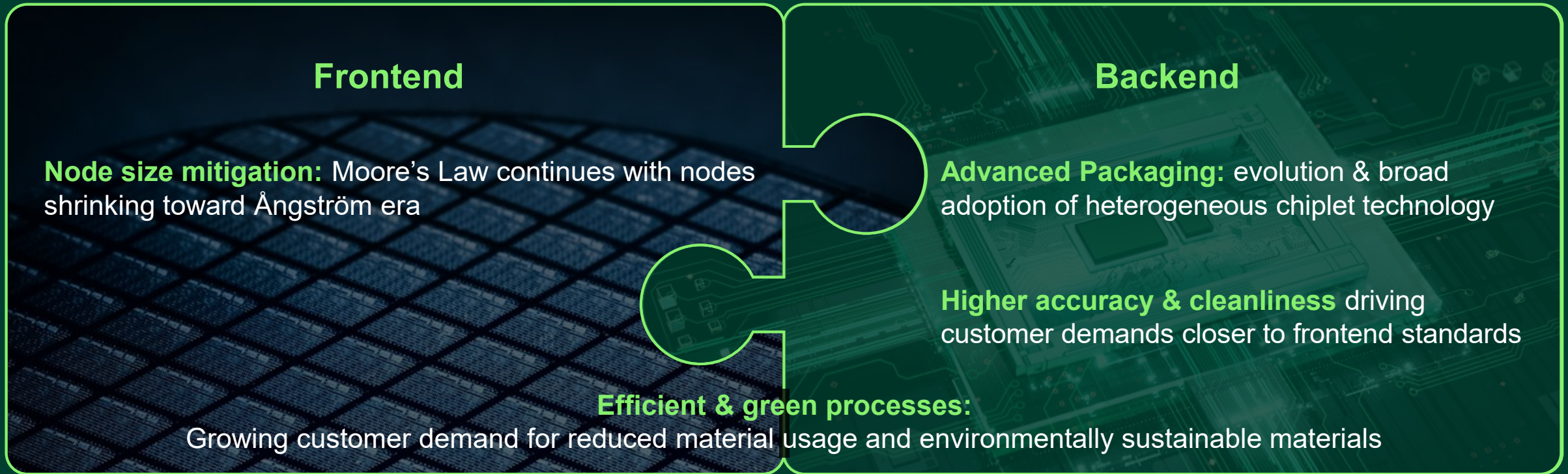
Semiconductor device revenue forecast (€bn) & key growth driver



¹ Based on USD values
Source: SUSS Research; market size based on Yole (2025); Note: USD/EUR forward exchange rate = 1.18, USD/EUR 2024 exchange rate = 1.08, Trend Selection – not exhaustive

Market segment	Growth-drivers
Computing & Data Storage	AI (Generative-, Agentic-, Physical-AI) Autonomous driving Industrial Automation / Internet of Things Metaverse (AR/VR) Key growth driver
Communications	Hyperconnectivity – 6G
Automotive	Software-Defined Vehicles / Autonom. driving Automotive Electrification
Industrial	Industrial Automation / Internet of Things Electrification / Green power generation
Consumer	Metaverse (AR/VR) Healthcare Wearables

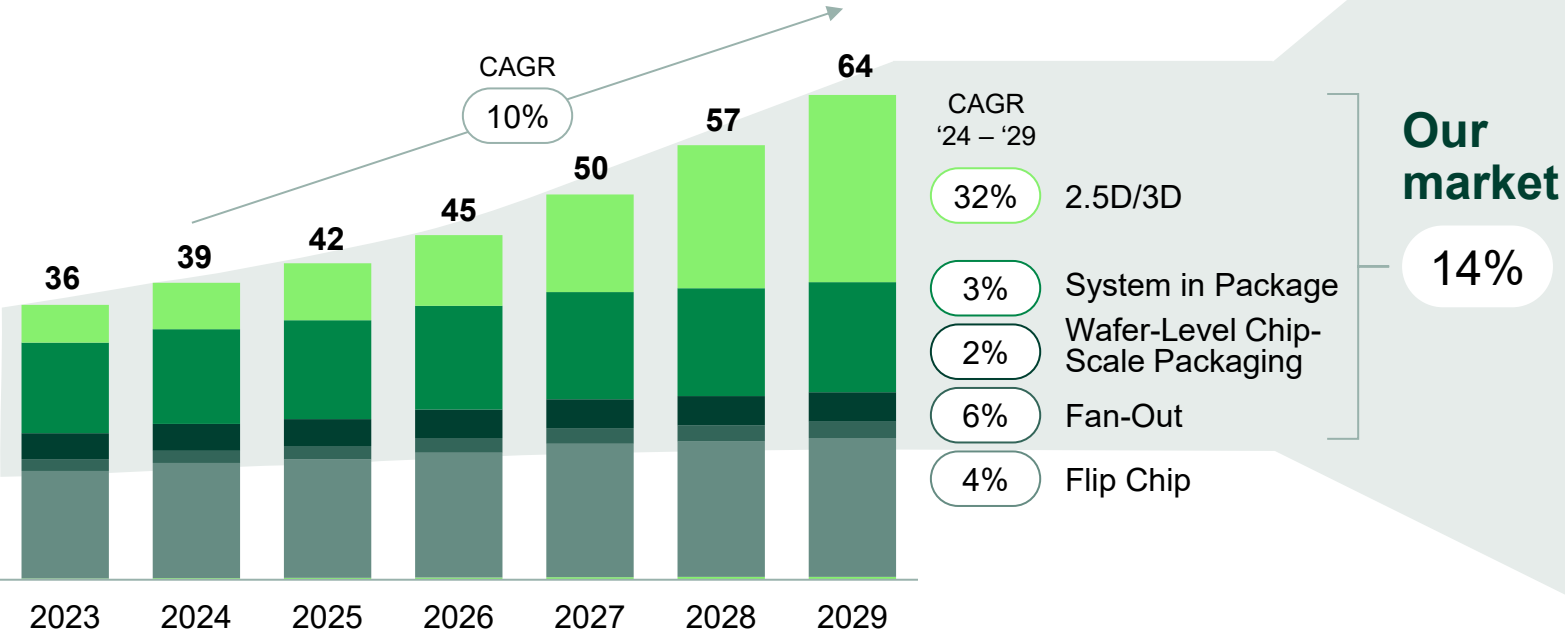
Rising application requirements are blurring the lines between Frontend & Backend territories – addressed in our Business Unit strategy



Advanced Packaging | Strong growth ahead – largely fueled by 2.5D and 3D packaging

As demand for high-performance computing rises, the **value in Advanced Packaging is shifting** toward high-end technologies

Advanced Packaging forecast [Million Wafer/Year]



XX% CAGR '24 – '29
Source: Yole (2024)

Interconnection of chips, wafers, and interposers (e.g., Redistribution Layers, Through-Interposer Via, Micro Bumps)

- > Patterning with our Lithography equipment: (Coater & Developer, Exposure equipment)

Structural support for thin elements

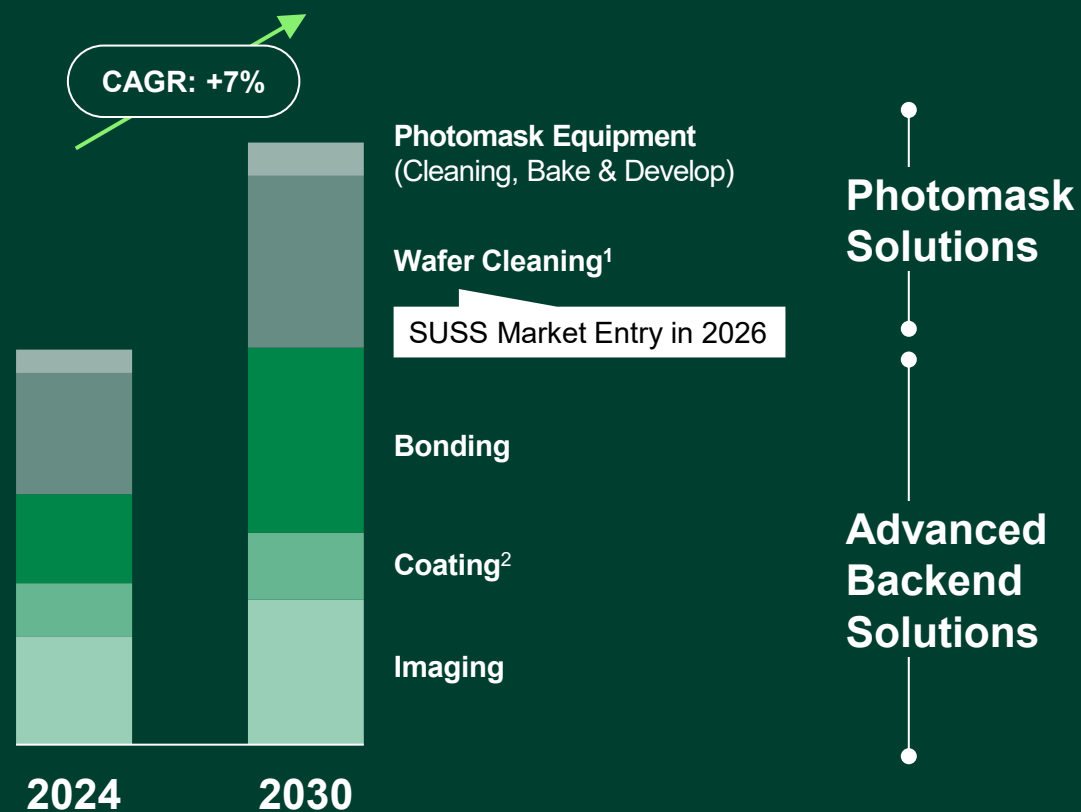
- > Temporary bonding on carrier wafer with our temporary bonding/de-bonding equipment

Mounting dies onto other dies or interposers

- > Interposer stacking and die attach/stacking with our permanent bonding equipment (incl. Hybrid Bonding)

Serviceable market is expected to grow by ~7% per annum through 2030

Serviceable Available Market (Revenue in €M)



¹ MEMS, Power, CIS & Advanced Packaging market reflected; ² Only Backend Coating market; Inkjet: Upside from expanding into additive manufacturing not reflected | Source: SUSS Research, primarily based on Yole



Photomask Equipment

- **High-End mask market leading growth**
- Mid-End mask market growing mid-to high single digits annually



Wafer Cleaning

- **Market entry with MEMS, Power & CMOS Image Sensors**; Expansion into Advanced Packaging with 300 mm tool planned (tool launch in 2027)
- Memory – future upside (not in market size reflected)



Bonding

- **Temporary Bonding will continue to grow** especially driven by high demand for AI
- **Hybrid Bonding with strong growth** ahead driven by advanced Logic & Memory



Coating

- **Advanced Packaging drives growth** in Backend Coating segment
- **Inkjet offers upside beyond traditional coating**, expanding into additive manufacturing



Imaging

- **Advanced Packaging fuels growth**; larger reticle-size dies supports adoption of full-field projection scanning

SUSS long term ambitions for 2030

€ 750 – 900 m

Sales
SUSS Ambition 2030

~ 8 –12% annual sales growth
compared to 2025

43 – 45%

Gross profit margin
SUSS Ambition 2030

+ ~8%-points GP margin
expansion compared to 2025

20 – 22%

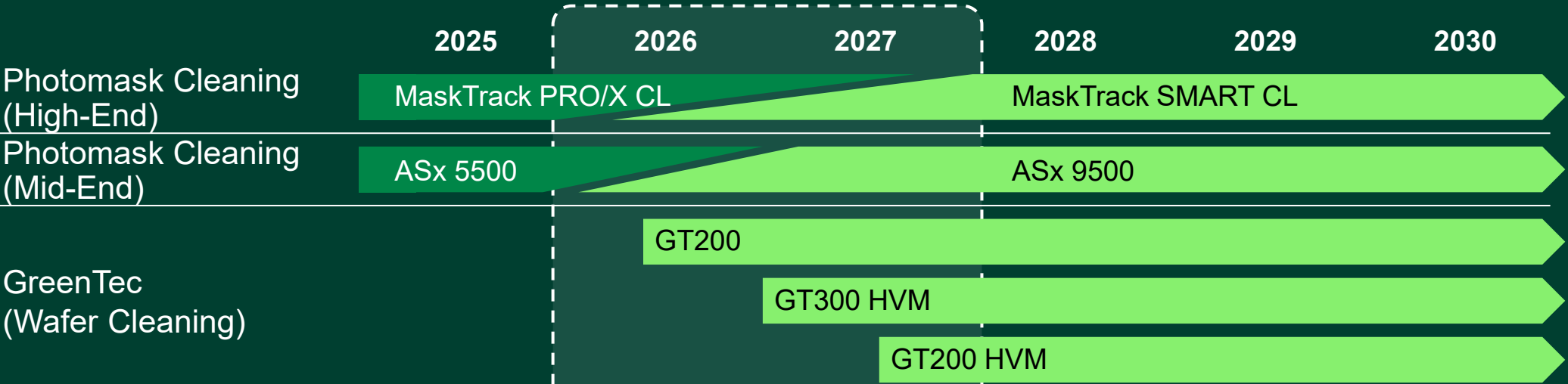
EBIT margin
SUSS Ambition 2030

+ ~8%-points EBIT margin
expansion compared to 2025

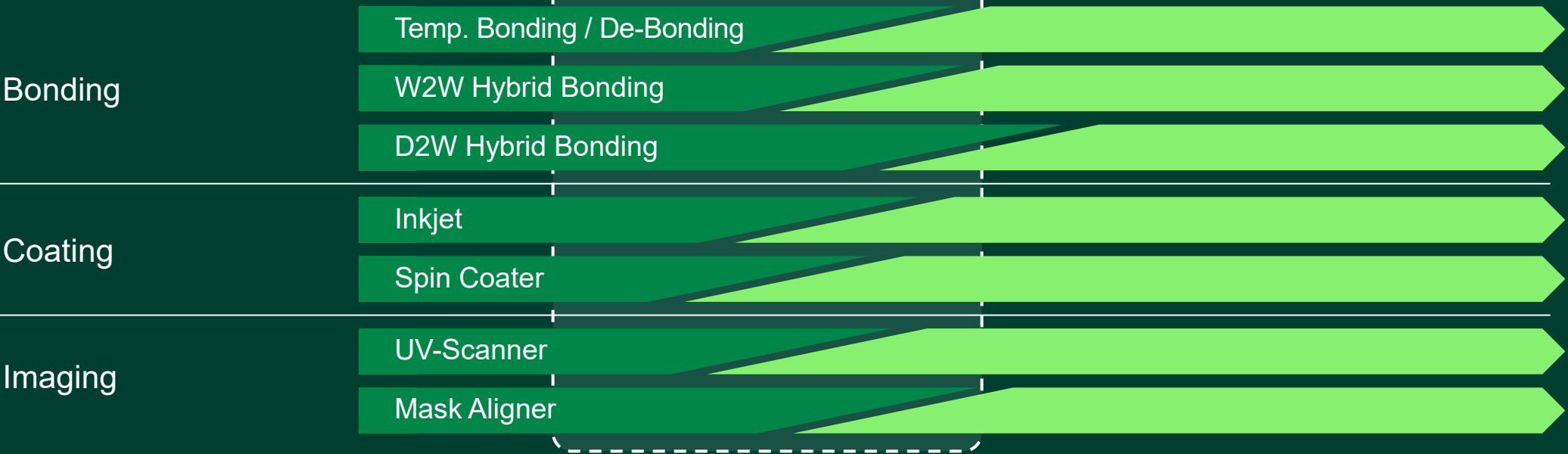
Upcoming new product introductions – initiating next growth phase



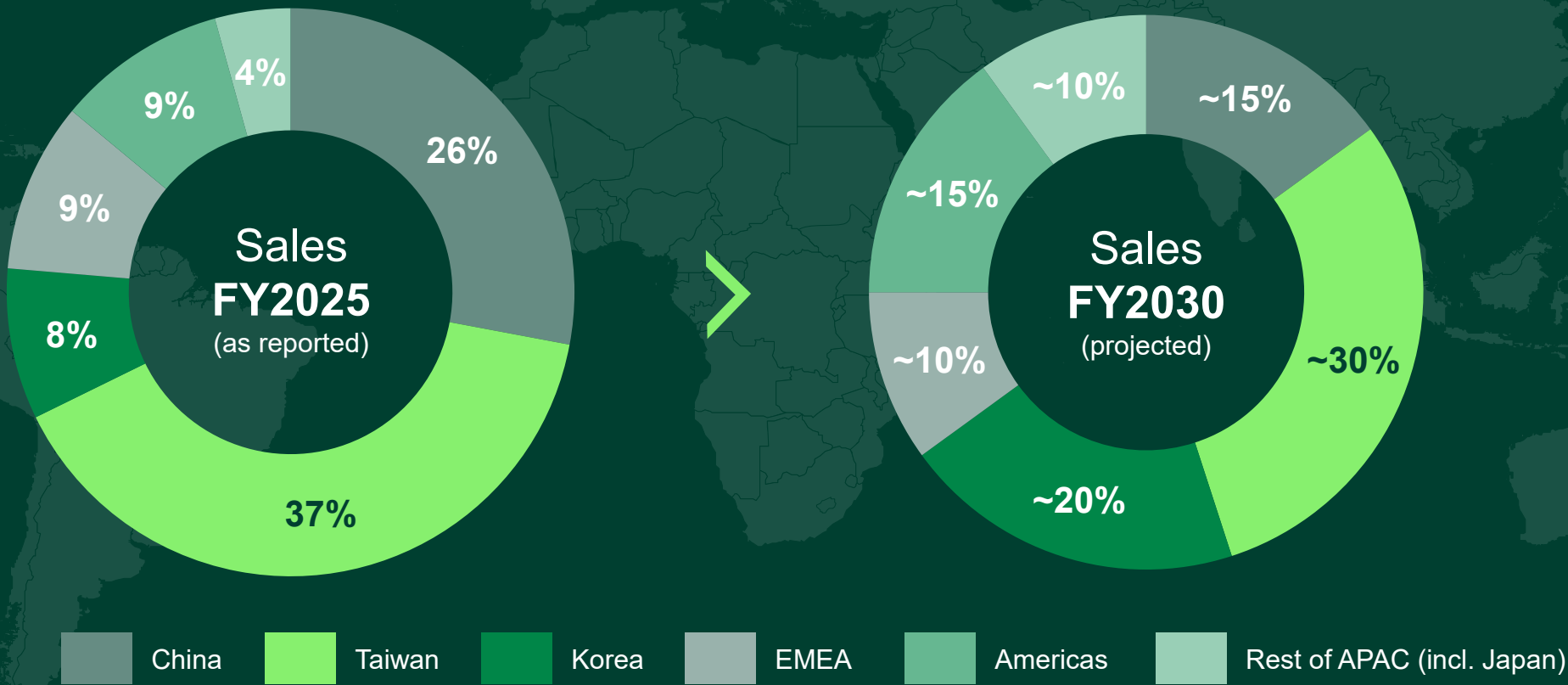
Photomask Solutions



Advanced Backend Solutions

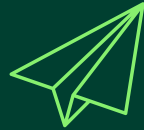


More diversified regional growth – with normalizing China share



SUSS – a valued partner in the semi ecosystem – Working alongside leading chip companies, as well as key research and industrial partners

We have expanded our global standing and have become a valued part of the semi ecosystem.



Our key success factors are:

- Focusing on market leaders
- Engaging into commercial and technology partnerships
- Creating customer intimacy through joint process development and key account management
- Local presence with highly qualified customer service and application support

Foundries and OSATs



Integrated Device Manufacturers (IDMs)



Technology and material partners

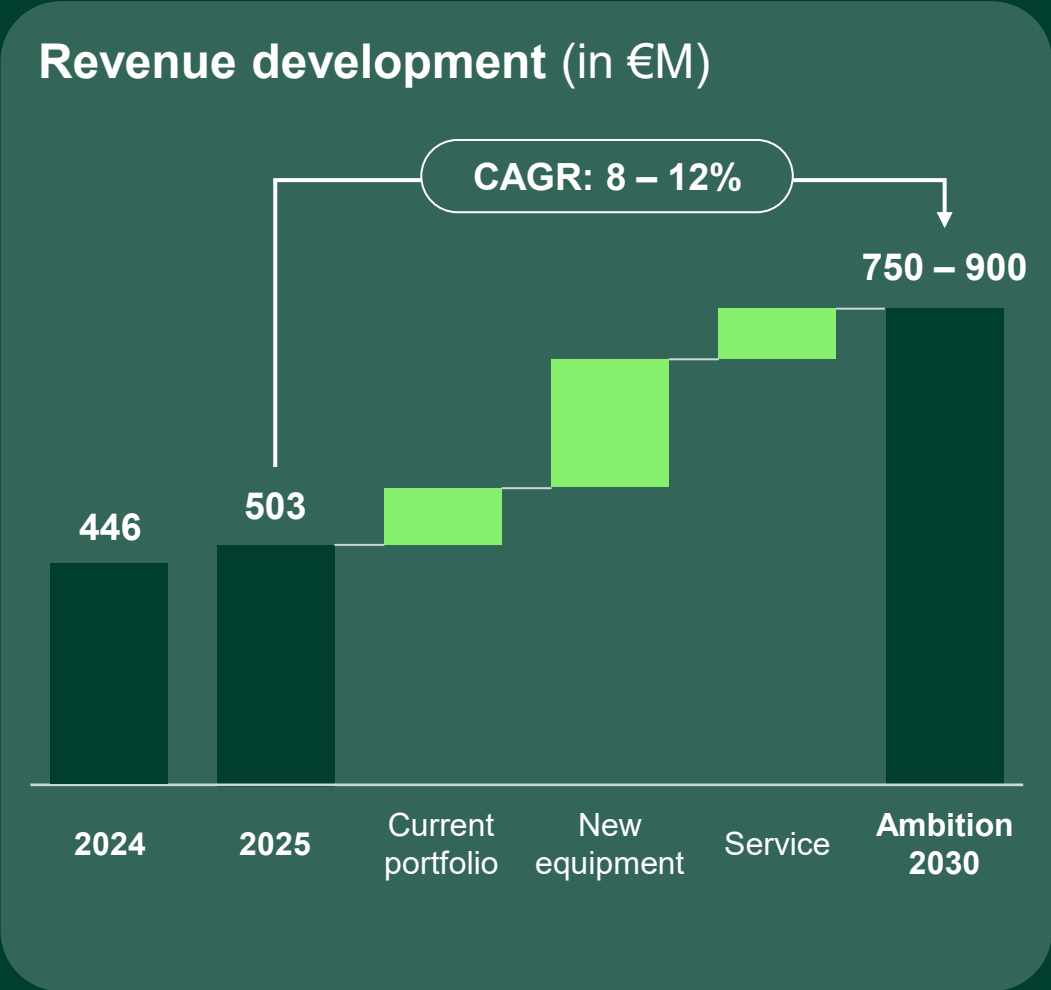


Academia, consortia and institutes



¹ 3DIC Advanced Manufacturing Alliance

Group growth based on strong evolving portfolio, new product introductions, and a strengthened service business



Current portfolio – key revenue drivers:

- Photomask Equipment** Remain #1 in high-end segment and expand leadership into mid-end segment
- Temporary Bonding** Sustaining leadership – especially in the HBM market segment
- UV-Scanner** Expand footprint in Advanced Packaging, leveraging strong position at the #1 foundry

New equipment – key revenue drivers :

- Wafer Cleaning** Enter the Wafer cleaning market with an innovative, cost-efficient & green solution
- Hybrid Bonding** Entry into Advanced Logic and HBM market, enabled by excellent technological performance
- Inkjet Coating** Shaping Inkjet market – a cost-efficient Coating solution and enabler for Additive Manufacturing

Service – key revenue drivers:

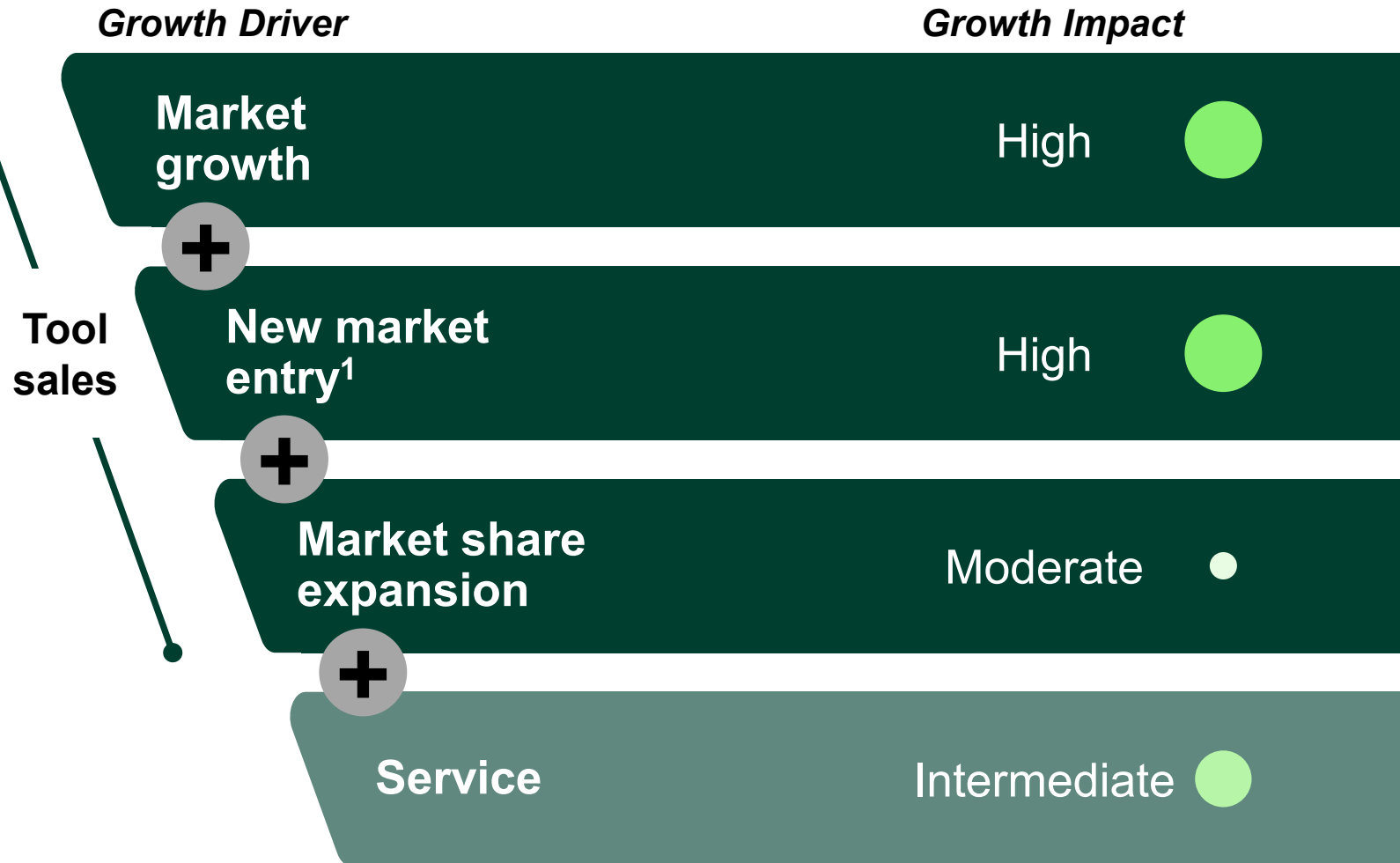
Growing Service revenue share from 18% to 25%, with Service now a strategic business contributor

Growth path underpinned by AI-driven market tailwind and continued expansion into new segments

 **SUSS**
2025 - 2030

8 – 12% sales
growth p.a.

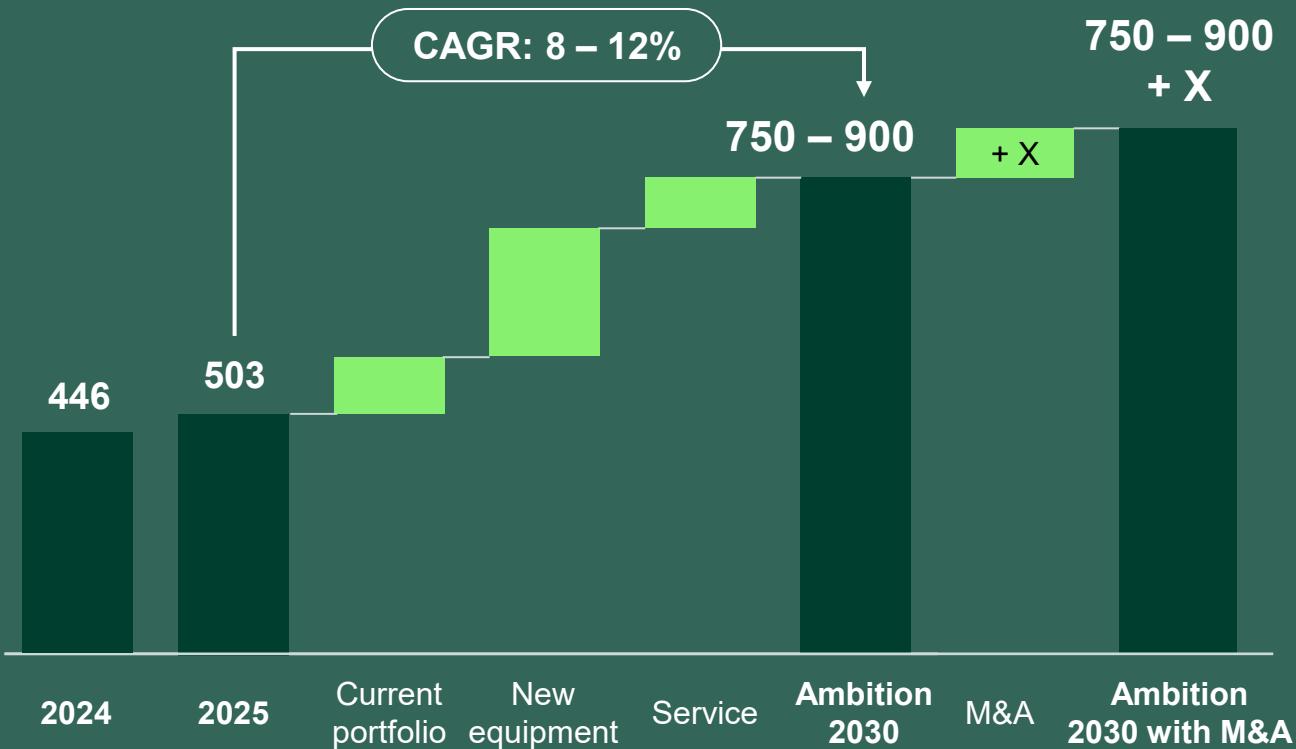
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1) Wafer Cleaning & Hybrid Bonding

Active pursuit of inorganic growth – we have the means and are looking for the right fit

Revenue development (in €M)



Strategically enhancement of existing portfolio



- Acquisition must support existing strategic priorities, not merely broaden the portfolio
- Acquisition should not structurally dilute our margin
- Carve out and integration efforts need to be manageable – culturally, operationally, and organizationally

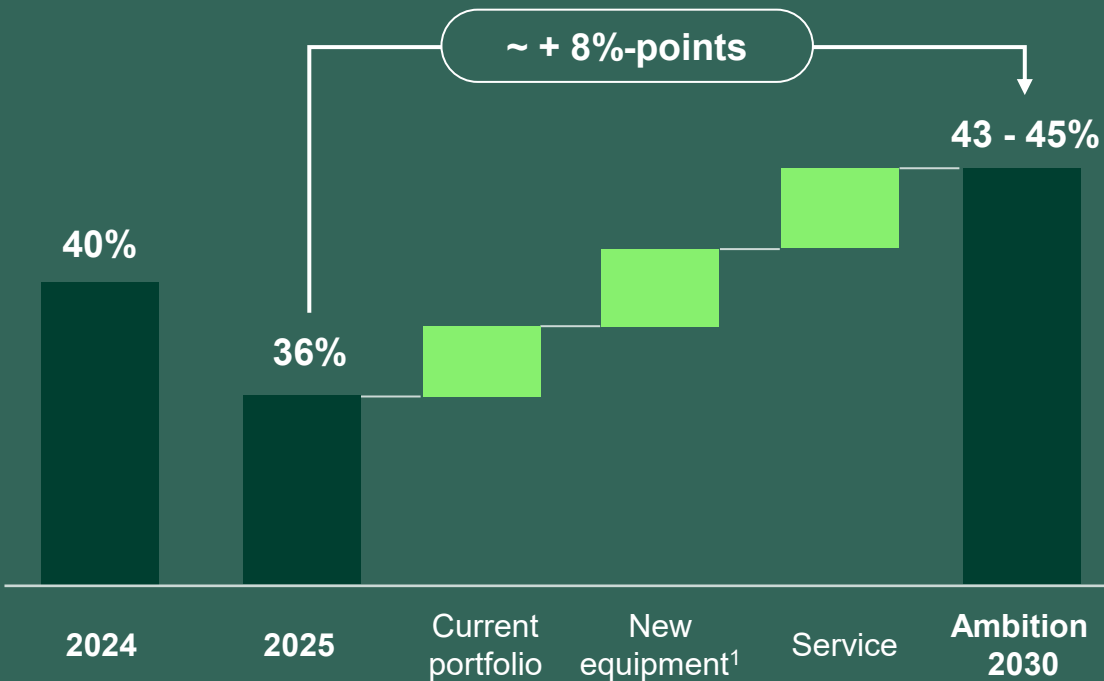
Acquisition of Know-How to accelerate product development



- In-house development not feasible, or significant time savings achievable through acquisition
- Clear path to monetization must be visible

Balanced margin expansion driven by the existing portfolio, new equipment platforms, and service

Gross profit margin development (in %)



1) Wafer Cleaning, Hybrid Bonding & Inkjet

Current (evolving) portfolio:

- New modular & standardized product generations (e.g. new Mask Cleaner, UV-Scanner & Mask Aligner)
- Optimized production network & further improved capacity utilization

New equipment:

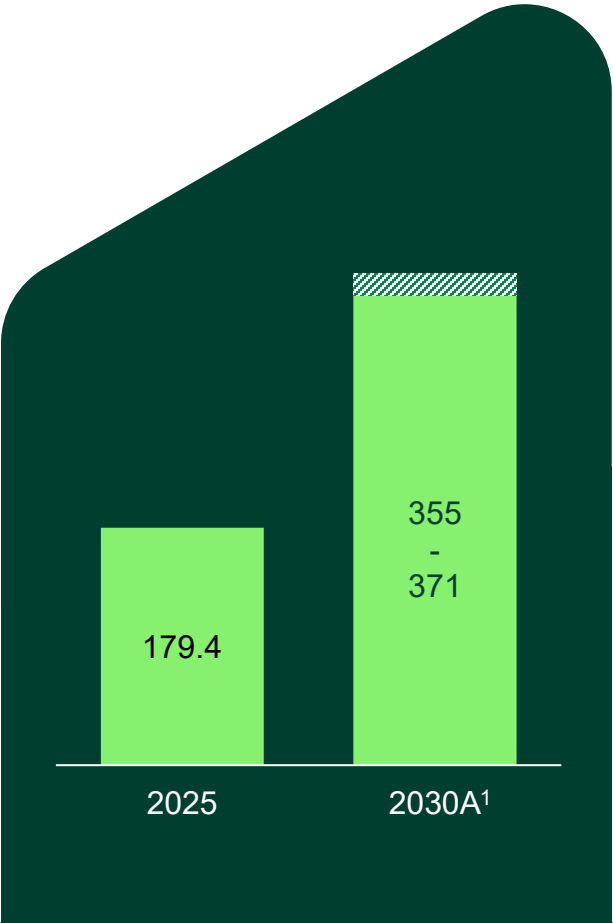
New products with higher margins than the current portfolio due to new equipment design (exception: Hybrid Bonder, where the die-bonding module is sourced externally)

Service:

Overall margin improvement through more strategic installed base management and focused service product portfolio

EBIT margin to benefit from higher business volume while increased R&D spend is covered by decline of SG&A expense ratio

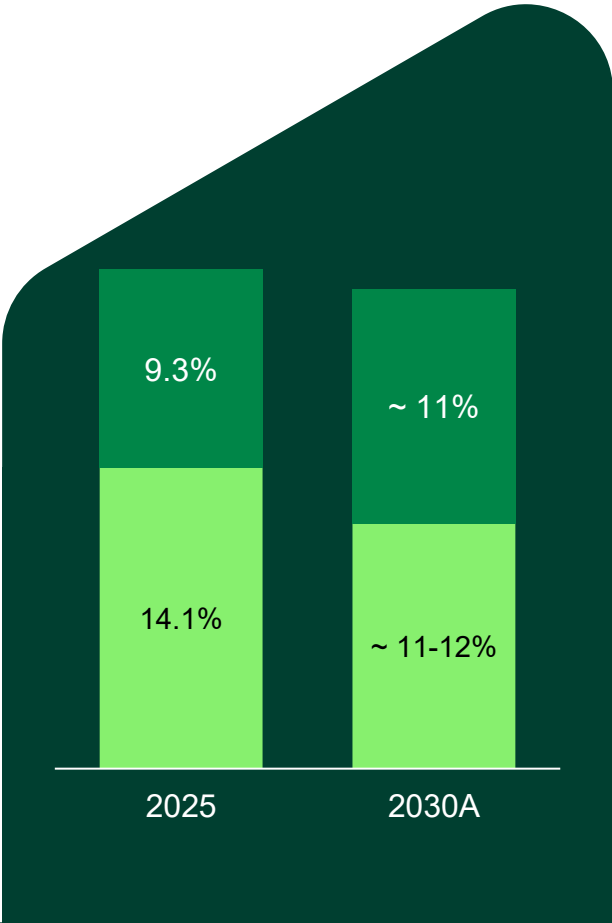
How to achieve the targeted EBIT margin of 20 – 22%



Benefiting from increase in gross profit

Gross profit has the potential to ~ **double** from 2025 to 2030, driven by larger business volume with improved profitability

¹ Gross profit is calculated based on the mid-point of the 2030 sales ambition.



Reduced SG&A expense ratio projected

- **R&D expense ratio** is expected to increase to support sales growth
- **SG&A expense ratio** is expected to decrease by ~ 2 to 3 %-points due to below-average increase in selling costs and admin functions

■ R&D expense ratio
■ SG&A expense ratio

Our ambition is to take SUSS to a new financial level by 2030

	FY 2025	FY 2030A
Sales	€503.2 million	€750 – 900 million
Sales growth	12.6% (YoY)	8 to 12% (CAGR 2025 – 2030A)
Gross profit margin (in %)	35.7%	43 to 45%
SG&A (in % of sales)	14.1%	~11 to 12%
R&D (in % of sales)	9.3%	~11%
EBIT margin (in %)	13.1%	20 to 22%
Free Cashflow (continuing operations)	€-22.6 million	~ €90 million
ROCE	21.3%	39 to 41%
CapEx	€23.2 million	~ €22 million (annual ø 2026 – 2030)
Tax rate	24.6%	~28% ¹

¹ The internal planning assumption for the tax rate is generally ~ 28%.

Investor Relations information

Conference and Roadshow Calendar

- **November 18–20, 2026**
Morgan Stanley European TMT Conference | Barcelona
- **November 23–24, 2026**
Deutsche Börse Equity Forum | Frankfurt (IR only)
- **November 25, 2026**
Goldman Sachs European AI & Semis Forum | London (IR only)

There may be changes to the SUSS conference and roadshow schedule.

Financial Calendar

- **November 5, 2026**
Quarterly Statement Q3 2026

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

Thank you

Growing Innovation



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